

Product Change /EOL NOTIFICATION**Issue Date: June 16, 2021****Change Type:**

New transceiver module design

Parts Affected:

1GE SX SFP, 850nm Multimode, -10 to 85°C & -40 to 85°C.

<u>Current Broadcom Part Number</u>	<u>New Broadcom Part Number</u>
AFBR-571xxxZ-xxx AFBR-570xxxZ-xxx	AFBR-5718xxxZ-xxx

Reason for Change:

New module design with non BRCM designed IC (laser driver/limiting amplifier & TIA) and alternate VCSEL & PIN.

In addition, manufacturing site will be in HiOptel/Venture which are also existing qualified CM for Broadcom.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There is no change to function, quality and reliability of products. The device specification will be identical as the current products. The delatch mechanism is consolidated to standard only (no bail option available).

Last time buy For Current Broadcom's PNs December 16, 2021**Last time Ship For Current Broadcom's PNs June 16, 2022**

Please note that orders will be accepted on a non-cancellable, non-returnable (NCNR) basis only. Broadcom reserves the right to limit last time buy quantities based on capacity and material availability.

Sample for new Broadcom PNs will be available now.

Product shipments using this change will begin on or after 14 September, 2021. Timing of shipment will depend on customer demand and inventory on-hand of current products.

Recommended Actions to be Taken by Customer:

Approve this PCN as soon as possible. Samples are available for evaluation if needed. Please contact local sales team to order samples.

Qualification Data

Table 1: Qualification Test Summary

Leg	Test	Reference	Condition	Sample Size	Test Points	Result (Fail/Pass)
1	High Temperature Operating Life	Section 5.18 (GR-468-CORE)	Tcase = 85°C, Vcc=3.3V, Release Point: 2000hrs	11	168, 500, 1000 & 2000 hrs	Pass
2	Biased Damp Heat	MIL-STD-202 Method 103	Ta = 85°C, RH = 85%, Vcc=3.3V, Release Point: 1000hrs,	11	168, 500, 1000 hrs	Pass
3	Un-Biased Damp Heat	MIL-STD-202 Method 103	Tcase=+85°C, RH = 85% Qual Release: 1000Hrs	11	168, 500, 1000 hrs	Pass
4	Temperature Cycling	MIL-STD-883 Method 1010	Ta = -40°C to +85°C, Release Point: 500 cyc,	11	0, 500 cyc	Pass
5a	Mechanical Shock (MS)	MIL-STD-883 Method 2002B	1500g, 0.5ms, 5shock/axis, 6axis	11	Post Shock test	Pass
5b	Mechanical Vibration (MV)	MIL-STD-883 Method 2007	20g, 20 to 2000Hz, 3axis, 4min/cycle, 4cycle/axis		Post Vibration	Pass
6	Biased Cyclic Moisture Resistance	MIL-STD-883 Method 1004	Ta = -10oC to +65oC, biased (Vcc= 3.3V) power On/Off @30min, 95%RH Released point: 20 cyc	11	0, 20 cyc	Pass
7	Dust Test	GR-326-CORE		10	Post Dust Test	Pass
8	ESD – HBM	JS-001-2017	1KV (High Speed Pins) 2KV (Low Speed Pins)	6	Post ESD	Pass
9	Good Device Analysis	FA Technique (X-ray, X-section etc)	NA	2	NA	Pass

These changes have been reviewed and approved by Broadcom engineers and managers per Broadcom procedure.

Please contact your Broadcom Limited field sales engineer for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.